



IFW

PATENT  
Docket No. 506212001200

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of:

Michihiko YANAGISAWA et al.

Serial No.: 10/671,483

Filing Date: September 29, 2003

For: MULTI-STEP DRY ETCHING  
METHOD FOR SOI WAFER

Examiner: Fernando L. Toledo

Group Art Unit: 2823

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Prior to the first examination on the merits of the elected claims, please amend this application as follows:

Amendments to the Specification begin on page 2.

Amendments to the claims begin on page 3.

Remarks begin on page 8.